

## SMAG Plastic-Encapsulate Diodes

### Schottky Rectifier Diode

#### Features:

- $I_{F(AV)}$  5A
- $V_{RRM}$  60V
- High surge current capability
- Polarity: Color band denotes cathode
- Low peak forward voltage

SMA



#### Applications:

- Rectifier

#### Marking

- KS56L:SS56L

#### Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	KS56L
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		60
Maximum RMS Voltage	$V_{RMS}$	V		42
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave · Resistance load · $T_a=100^{\circ}C$	5.0
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave · 1 cycle · $T_a=25^{\circ}C$	120
Junction Temperature	$T_J$	$^{\circ}C$		-55 ~ +150
Storage Temperature	$T_{STG}$	$^{\circ}C$		-55 ~ +150

#### Electrical Characteristics ( $T=25^{\circ}C$ Unless otherwise specified)

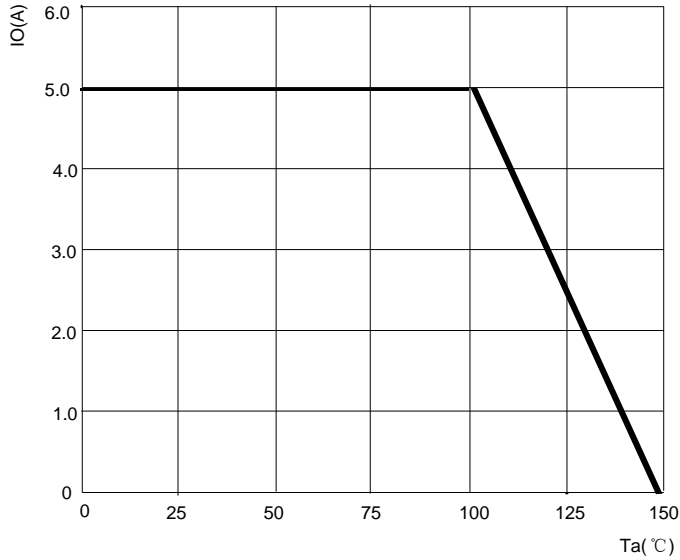
Item	Symbol	Unit	Test Condition	KS56L	
Peak Forward Voltage	$V_F$	V	$I_F=1.0A$	0.34(TYP) 0.40(MAX)	
			$I_F=3.0A$	0.42(TYP) 0.45(MAX)	
			$I_F=5.0A$	0.47(TYP) 0.50(MAX)	
Peak Reverse Current	$I_{RRM1}$	mA	$V_{RM}=V_{RRM}$	$T_a=25^{\circ}C$	0.05(TYP) 0.3(MAX)
	$I_{RRM2}$			$T_a=100^{\circ}C$	50
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^{\circ}C/W$	Between junction and ambient	60	
	$R_{\theta J-L}$		Between junction and lead	20	

#### Notes:

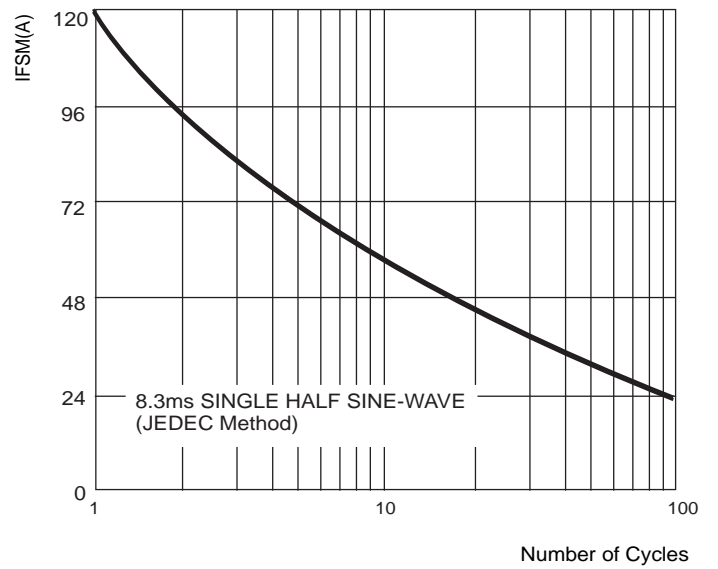
Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

**Typical Characteristics**

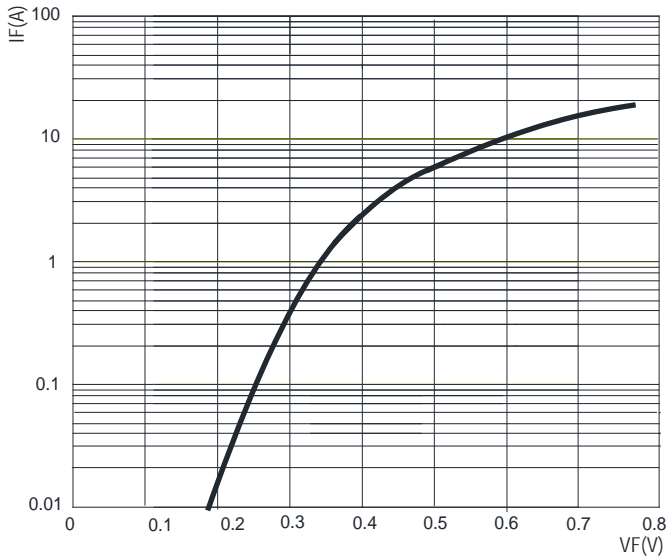
**FIG.1: FORWARD CURRENT DERATING CURVE**



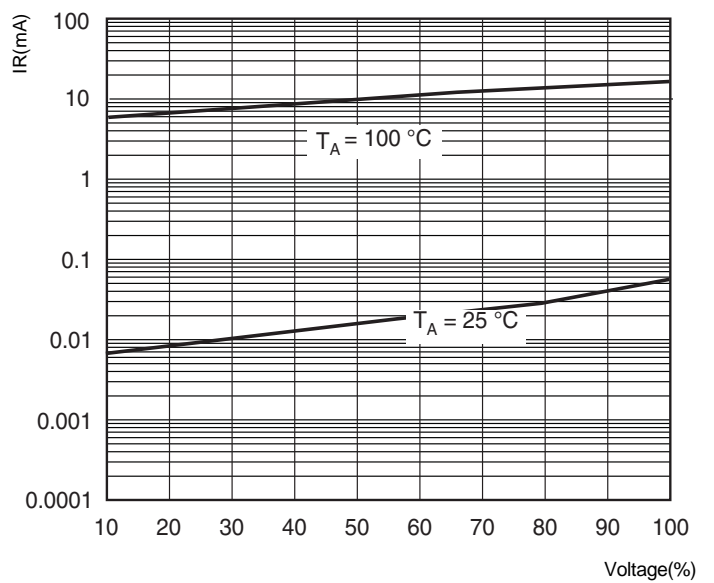
**FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



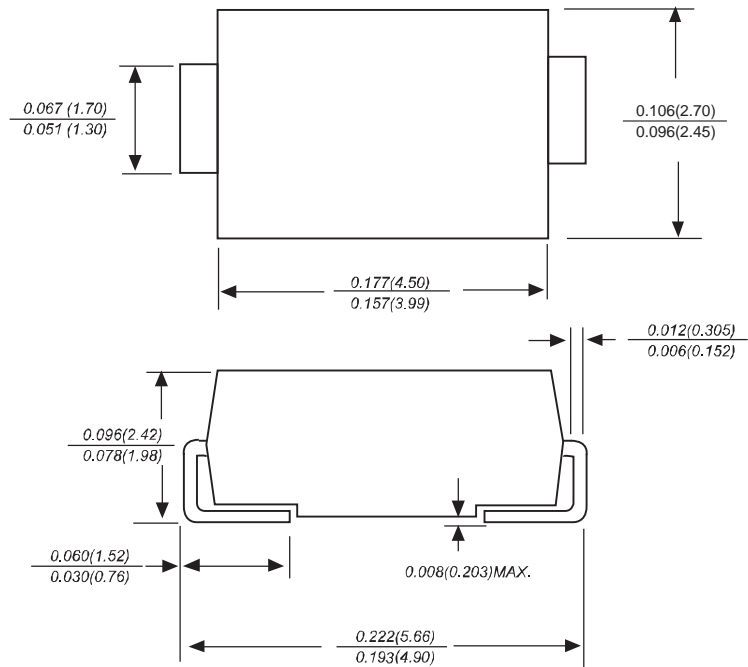
**FIG.3: TYPICAL FORWARD CHARACTERISTICS**



**FIG.4: TYPICAL REVERSE CHARACTERISTICS**

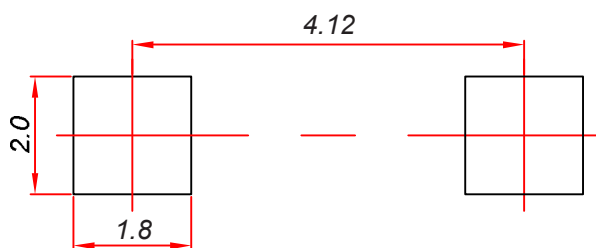


**SMAG Package Outline Dimensions**



*Dimensions in inches and (millimeters)*

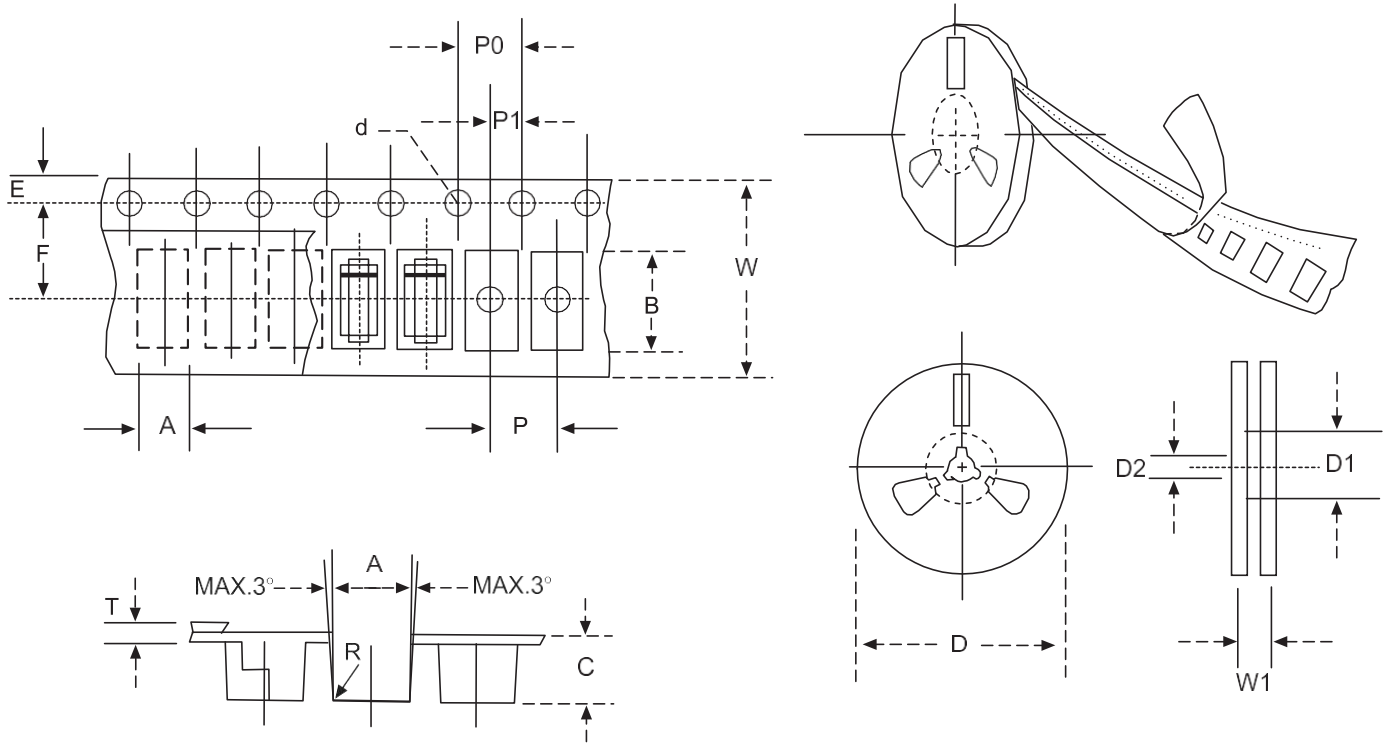
**SMAG Suggested Pad Layout**



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$  mm.
3. The pad layout is for reference purposes only.

**Reel Taping Specifications For Surface Mount Devices-SMAG**



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11±0.079)
Reel inner diameter	D1	75 ±1.0 ( 2.95 ±0.039 )
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011 ±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.